Mounting Wafer on a Dicing Tape - Standard Operating Procedure

1. Place the metal frame on a mounting station
2. Place the wafer with device side down in the middle of the metal frame
3. Switch on the vacuum to hold the wafer
4. Pull the tape over the wafer and metal frame
5. Roll the roller back and forth
6. Lower the cutting panel and cut the tape around metal frame
7. Cut the tape in the back
8. Remove the excess tape
9. Turn off the vacuum and pick up mounted wafer (Workpiece)